

INTERNATIONAL STANDARD



**Process management for avionics – Counterfeit prevention –
Part 1: Avoiding the use of counterfeit, fraudulent and recycled electronic
components**

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Edition 1.1 2024-09
CONSOLIDATED VERSION

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PROCESS MANAGEMENT FOR AVIONICS –
COUNTERFEIT PREVENTION –****Part 1: Avoiding the use of counterfeit, fraudulent and
recycled electronic components**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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This consolidated version of the official IEC Standard and its amendment has been prepared for user convenience.

IEC 62668-1 edition 1.1 contains the first edition (2019-09) [documents 107/335/CDV and 107/346A/RVC] and its amendment 1 (2024-09) [documents 107/416/FDIS and 107/421/RVD].

In this Redline version, a vertical line in the margin shows where the technical content is modified by amendment 1. Additions are in green text, deletions are in strikethrough red text. A separate Final version with all changes accepted is available in this publication.

International Standard IEC 62668-1 has been prepared by IEC technical committee 107: Process management for avionics.

This first edition cancels and replaces the third edition of IEC TS 62668-1 published in 2016. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) added a reference to AS/EN/JISQ 9100 and AS/EN/JISQ 9110 which contain anti-counterfeit requirements which may be used to satisfy the requirements of 4.2;
- b) added reference to USA DFAR rule 252.246.7008 and to UK Defence Standard 05-135;
- c) added reference to more GAO, OECD and ICC reports in 4.5.1;
- d) updated weblinks and other references;
- e) added new Annex E with figures describing how anti-counterfeit documents can be used in supply chains;
- f) added a reference to the new IECQ OD 3702 traceability audit;
- g) added new definition for re-manufactured components with a warning that these are not recommended.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62668 series, published under the general title *Process management for avionics – Counterfeit prevention*, can be found on the IEC website.

The committee has decided that the contents of this document and its amendment will remain unchanged until the stability date indicated on the IEC website under webstore.iec.ch in the data related to the specific document. At this date, the document will be

- reconfirmed,
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PROCESS MANAGEMENT FOR AVIONICS – COUNTERFEIT PREVENTION –

Part 1: Avoiding the use of counterfeit, fraudulent and recycled electronic components

1 Scope

This part of IEC 62668 defines requirements for avoiding the use of counterfeit, recycled and fraudulent components used in the aerospace, defence and high performance (ADHP) industries. It also defines requirements for ADHP industries to maintain their intellectual property (IP) for all of their products and services. The risks associated with purchasing components outside of franchised distributor networks are considered in IEC 62668-2. Although developed for the avionics industry, this document can be applied by other high performance and high reliability industries at their discretion.

NOTE IEC 62668 (all parts) does not address the restriction on the re-use of a component in maintenance, repair and overhaul (MRO) operations and only addresses MRO activities when they are under the OEM's responsibility.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 62239-1, *Process management for avionics – Management plan – Part 1: Preparation and maintenance of an electronic components management plan*

IEC 62668-2, *Process management for avionics – Counterfeit prevention – Part 2: Managing electronic components from non-franchised sources*

ISO 9001, *Quality management systems – Requirements*

AS/EN/JISQ 9100, *Quality Management Systems – Requirements for Aviation, Space and Defense Organizations*

AS/EN/JISQ 9110, *Quality Maintenance Systems – Aerospace – Requirements for Maintenance Organizations*

3 Terms, definitions and abbreviated terms

3.1 Terms and definitions

For the purposes of this document, the following terms and definitions apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1.1

aftermarket source

reseller which may or may not be under contract with the original component manufacturer (OCM), or is sometimes a component “re-manufacturer”, under contract with the OCM

Note 1 to entry: The reseller accumulates inventories of encapsulated or non-encapsulated (wafer) components whose end of life date has been published by the OCM. These components are then resold at a profit to fill a need within the market for components that have become obsolete.

3.1.2

broker

individual or corporate organization that serves as an intermediary between buyer and seller

Note 1 to entry: In the electronic component sector a broker specifically seeks to supply obsolete or hard to find components in order to turn a profit. To do so it may accumulate an inventory of components considered to be of strategic value or may rely on inventories accumulated by others. The broker operates within a worldwide component exchange network.

3.1.3

COTS product

commercial off-the-shelf product

one or more components, assembled and developed for multiple commercial consumers, whose design and/or configuration is controlled by the manufacturer's specification or industry standard

Note 1 to entry: COTS products can include electronic components, subassemblies or assemblies, or top level assemblies. Electronic COTS subassemblies or assemblies include circuit card assemblies, power supplies, hard drives, and memory modules. Top-level COTS assemblies include a fully integrated rack of equipment such as raid arrays, file servers to individual switches, routers, personal computers, or similar equipment.

Note 2 to entry: This note applies to the French language only.

3.1.4

counterfeit, verb

action of simulating, reproducing or modifying a material good or its packaging without authorization

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Note 1 to entry: It is the practice of producing products which are imitations or are fake goods or services. This activity infringes the intellectual property rights of the original manufacturer and is an illegal act. Counterfeiting generally relates to wilful trademark infringement.

3.1.5

counterfeited component

material good imitating or copying an authentic material good which may be covered by the protection of one or more registered or confidential intellectual property rights

Note 1 to entry: A counterfeited component is one whose identity or pedigree has been altered or misrepresented by its supplier.

Identity = original manufacturer, part number, date code, lot number, testing, inspection, documentation or warranty, etc.

Pedigree = origin, ownership history, storage, handling, physical condition, previous use, etc.

Note 2 to entry: When a material good has no registered or confidential intellectual property rights, then the material good has no intellectual property protection. Examples include situations where the original component manufacturer (OCM) has ceased to trade and has not sold or passed on the intellectual property rights to another entity.

3.1.6

customer device specification

device specification written by a user and agreed by the supplier

3.1.7 customer user

original equipment manufacturer (OEM) which purchases electronic components, including integrated circuits and/or semiconductor devices compliant with this document, and uses them to design, produce, and maintain systems

3.1.8 data sheet

document prepared by the manufacturer that describes the electrical, mechanical, and environmental characteristics of the component

3.1.9 franchised distributor or agent

individual or corporate organization that is legally independent from the franchiser (in this case the electronic component manufacturer or OCM) and agrees under contract to distribute products using the franchiser's name and sales network

Note 1 to entry: Distribution activities are carried out in accordance with standards set and controlled by the franchiser. Shipments against orders placed can be despatched either directly from the OCM or the franchised distributor or agent. In other words, the franchised distributor enters into contractual agreements with one or more electronic component manufacturers to distribute and sell the said components. Distribution agreements may be stipulated according to the following criteria: geographical area, type of clientele (avionics for example), maximum manufacturing lot size. Components sourced through this route are protected by the OCM's warranty and supplied with full traceability.

3.1.10 fraudulent component

electronic component produced or distributed either in violation of regional or local law or regulation, or with the intent to deceive the customer

Note 1 to entry: This includes but is not limited to the following which are examples of components which are fraudulently sold as new ones to a customer:

- 1) a stolen component;
- 2) a component scrapped by the original component manufacturer (OCM) or by any user;
- 3) a recycled component, that becomes a fraudulent recycled component when it is a disassembled (for example disassembled from a PCB assembly) component resold as a new component (see Figure 1), where typically there is evidence of prior use and rework (e.g. solder, re-plating or lead re-attachment activity) on the component package terminations;
- 4) a counterfeit component, a copy, an imitation, a full or partial substitute of brands;
- 5) fraudulent designs, models, patents, software or copyright sold as being new and authentic. For example: a component whose production and distribution are not controlled by the original manufacturer;
- 6) unlicensed copies of a design;
- 7) a disguised component (re-marking of the original manufacturer's name, reference date/code or other identifiers etc.), which may be a counterfeit component (see Figure 1);
- 8) a component without an internal silicon die or with a substituted silicon die which is not the original manufacturer's silicon die.

3.1.11 intellectual property

creations of the mind such as inventions, literary and artistic works, and symbols, names, images, and designs used in commerce

Note 1 to entry: This is property created through intellectual or creative activity.

Note 2 to entry: It includes patents, trademarks, copyright and designs. It can be owned, rented out, licensed, sold or given away.

3.1.12
microcircuit
component
device

electrical or electronic device that is not subject to disassembly without destruction or impairment of design use and is a small circuit having a high equivalent circuit element density which is considered as a single part composed of interconnected elements on or within a single substrate to perform an electronic circuit function

Note 1 to entry: This excludes printed wiring boards/printed circuit boards, circuit card assemblies and modules composed exclusively of discrete electronic components.

3.1.13
MRO
maintenance, repair and overhaul

operations, such as tests, measurements, replacements, adjustments, and repairs, intended to retain or restore a functional unit in or to a specified state in which the unit can perform its required functions

Note 1 to entry: This activity includes inspection, rebuilding, alteration and the supply of spare parts, accessories, raw materials, adhesives, sealants, coatings and consumables.

Note 2 to entry: This note applies to the French language only.

3.1.14
non-franchised distributor
company which does not fall under a franchised distributor or OCM

Note 1 to entry: These distributors may purchase components from component manufacturers, franchised distributors, or through other supply channels (open markets). These distributors cannot always provide the guarantees and support provided by the franchised distributor network; components sourced through this source are usually protected by the source's warranty only.

Note 2 to entry: Some non-franchised distributors are able to purchase traceable components from the OCM or their franchised distributors and to provide traceability paperwork and/or are able to return stock for investigation to the OCM. Such non-franchised distributors can satisfy the USA DFARS 252.246.7008 requirements (see A.8.10).

3.1.15
OCM
original component manufacturer
company specifying and manufacturing the electronic component

Note 1 to entry: This note applies to the French language only.

3.1.16
OEM
original equipment manufacturer
manufacturer which defines the electronic subassembly that includes the electronic components or defines the components used in an assembly and/or test specification

Note 1 to entry: This note applies to the French language only.

3.1.17
piracy
willful copyright infringement

3.1.18
re-manufactured component
recycled element
electronic component that includes a recycled silicon die or technology element as documented and disclosed by the electronic component re-manufacturer and that is fully tested before being sold

Note 1 to entry: Examples include a silicon or other die extracted from another electronic component, either new or used, which is externally marked and disclosed using the re-manufacturer's name, logo and different part number.

Note 2 to entry: Re-manufacturing an electronic component can necessitate the original engineering data and schematics of the product. This does not mean that a re-manufactured product is identical to the new product.

Note 3 to entry: Electronic re-manufactured components often come with warranties.

3.1.19 reseller

general supplier which offers a selection of electronic components to order from a catalog

3.1.20 recycled component

electrical component removed from its original product or assembly and available for reuse

Note 1 to entry: The component has authentic logos, trademarks and markings. However, it typically has no output to measure the useful life remaining for its reuse. A recycled component can fail earlier than a new one when re-assembled into another product or assembly. A recycled component may also be physically damaged or damaged through electro static discharge (ESD) during the removal process.

3.1.21 semiconductor

electronic component in which the characteristic distinguishing electronic conduction takes place within a semiconductor

Note 1 to entry: This includes semiconductor diodes which are semiconductor devices having two terminals and exhibiting a nonlinear voltage-current characteristic and transistors which are active semiconductor devices capable of providing power amplification and having three or more terminals.

3.1.22 subcontractor

manufacturer of electronic subassemblies or supplier manufacturing items in compliance with customer design data pack and drawings, and under the authority of the OEM

Note 1 to entry: This supplier can potentially procure all or part of the electronic components required to produce a subassembly and is often referred to as the contract electronic manufacturer (CEM) or electronics manufacturing services (EMS).

3.1.23 supplier

company which provides to another an electronic component which is identified by the logo or name marked on the device

Note 1 to entry: A supplier can be an OCM, a franchised distributor or agent, a non-franchised distributor, broker, reseller, OEM, CEM, and EMS, etc.

3.1.24 suspect component

electronic component which has lost supply chain traceability back to the original manufacturer and which may have been misrepresented by the supplier or manufacturer and may meet the definition of fraudulent or counterfeit component

Note 1 to entry: Suspect components may include but are not limited to:

- 1) counterfeit components;
- 2) recycled components coming from uncontrolled recycling operations carried outside of the OEM, franchised network and OEM business where typically it has been fraudulently sold to the OEM as being in a new unused condition.

3.1.25 traceability

ability to have, for an electronic component, its full trace back to the original component manufacturer